MICROCHIP

Semiconductor Device Type:	T6C	TO-220-2-MatteTin			
Basic Substance	**CAS Number**	**"Contained In" Sub-Component**	**% Total Weight**	**mg/part**	**ppm**
Silicon Carbide	409-21-2	Die	0.23	4.50	2321
Copper	7440-50-8	Leadframe	69.15	1340.58	691520
Iron	7439-89-6	Leadframe	0.11	2.06	1062
Nickel	7440-02-0	Leadframe	1.49	28.81	14862
Phosphorus	7723-14-0	Leadframe	0.03	0.55	283
Lead	7439-92-1	Die attach material	0.86	16.71	8621
Silver	7440-22-4	Die attach material	0.02	0.44	226
Tin	7440-31-5	Die attach material	0.02	0.35	181
Aluminum	7429-90-5	Wire	0.06	1.20	619
Impurity	Trade Secret	Wire	0.00	0.00	0
Silicon dioxide	7631-86-9	Mold Compound	20.15	390.68	201524
Formaldehyde, polymer with chloromethyl oxirane and 2-methylphenol	29690-82-2	Mold Compound	3.29	63.81	32916
Phenol-formaldehyde polymer	9003-35-4	Mold Compound	3.29	63.81	32916
Carbon black	1333-86-4	Mold Compound	0.13	2.60	1343
Tin	7440-31-5	Lead finish	1.16	22.50	11606
		TOTALS:	**100.00**	**1938.60**	**1,000,000**

1938.60 mg Total Mass

Package Homogeneous Materials

4.50	(mg) Total	Die	% of Total Weight	0.23
	Silicon Carbide	409-21-2	100.00	
		Total	**100.00**	
1372.00	**(mg) Total**	**Leadframe**	**% of Total Weight**	**70.77**
	Copper	7440-50-8	97.71	
	Iron	7439-89-6	0.15	
	Nickel	7440-02-0	2.10	
	Phosphorus	7723-14-0	0.04	
		Total	**100.00**	
17.50	**(mg) Total**	**Die attach material**	**% of Total Weight**	**0.90**
	Lead	7439-92-1	95.50	
	Silver	7440-22-4	2.50	
	Tin	7440-31-5	2.00	
		Total	**100.00**	
1.20	**(mg) Total**	**Wire**	**% of Total Weight**	**0.06**
	Aluminum	7429-90-5	99.99	
	Impurity	Trade Secret	0.01	
		Total	**100.00**	
520.90	**(mg) Total**	**Mold Compound**	**% of Total Weight**	**26.87**
	Silicon dioxide	7631-86-9	75.00	
	Formaldehyde, polymer with chloromethyl oxirane and 2-methylphenol	29690-82-2	12.25	
	Phenol-formaldehyde polymer	9003-35-4	12.25	
	Carbon black	1333-86-4	0.50	
		Total	**100.00**	
22.50	**(mg) Total**	**Lead finish**	**% of Total Weight**	**1.16**
	Tin	7440-31-5	100.00	
1938.60		**Total**	**100.00**	100.00

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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